

Engineering Design

GLAST Large Area Telescope Engineering Meeting

Flight Hardware Buys before CDR

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Flight Hardware Buys -- ACD

•	Composite Shell	
•	Composite Shell to Base Frame Flexures	
•	TDA's including connectors	
•	TDA tiedowns (flexures between shell and TDA's) with fasteners	
•	Micrometeoroid Shield and Thermal Blanket standoffs and caps	
•	Micrometeoroid Shield and Thermal Blanket materials	
•	Base Frame (channels, closeout covers, mid-span snubbers, connector brackets & fasteners)	
•	Electronics Chassis mechanical components (Frame, HVBS covers, FREE board standoffs, HV rail cover, fasteners)	
•	PMT housing with Resistor Network (RN) enclosure	
•	Fiber Cables (fibers, wrappings, springs, PMT bushings, cookies, &	
	PMT caps)	
•	HVBS's	
•	PMT's	
•	FREE PCB's	
•	All FREE Board electrical components including ASICs (GAFEs and GARCs)	
•	Resistor Network PCBs and electrical components	
•	Bulkhead connectors	
•	All electrical wiring	



Flight Hardware Buys -- TKR

Item	Lead Time	Date Needed
SSDs	NA	ongoing
Carbon-Carbon blanks	NA	ongoing
Sidewall Material (Italian responsibility)	2 to 4 weeks	Combined EM,
		2/14/03, and Flight
		purchase
Aluminum cores	3 to 4 weeks	March 3
Face sheet prepreg (Italian responsibility)	Sandro plans to	March 3
	start with materials	
	already in hand	
Aluminum inserts, 3mm and 4mm (Italian	2 to 4 weeks	March 3
responsibility)		
Bias flex circuits	4 to 6 weeks	April, May?
Tower-assembly sidewall fasteners	NA	Not urgent but
		already procured
Thin tungsten (Italian responsibility)	4 weeks	April, May?
Thick tungsten	4 weeks	April, May?
Pitch-adapter flex circuits	4 to 6 weeks	January 27
MCM printed wiring boards	4 to 6 weeks	January 27
MCM SMT parts		February 10
Nano Connectors	8 weeks	February 10
Connector savers (not flight hardware)	8 weeks	March 28
Poly fuses		February 10
HV caps		February 10
GTFE ASICs	NA	March 31
GTRC ASICs	NA	March 31



Flight Hardware Buys -- CAL

- Csl crystals, LAT-DS-00820-02, The contract w/ amcrys-H has been in place since April,2001 for em and flt crystals. the referenced spec are the negotiated changes from the original contract. deliveries of flt crystals scheduled in mid march.
- 2. Dual PIN Photodiode, LAT-DS-00209-11. We need to start the order in mid Feb.
- 3. Fasteners from the CAL Inorganic Materials List, long lead items.
- 4. PrePreg carbon composite material for structure from CAL Polymeric materials list.
- 5. VM2000 optical wrap material. This is to capture the material before 3M changes it.
- 6. ASICs, GCFE and GCRC perhaps the flight orders have already been placed.
- 7. Flight AFEE-TEM electrical cables (manufactured from parts on the EEE parts list)
- 8. All EEE Parts on the CAL EEE parts list (attached below).



Flight Hardware Buys -- Mechanical

4x4 grid raw mat'l, 2 plates

downspout & X-LAT heat pipe extrusions

custom bolts for CAL baseplate to grid attachment

Top flange extrusions

VCHP extrusions

VCHP reservoirs

SS thermostats

planned

LM has ordered

planned

LM Contract

LM Contract

LM Contract

LM Contract



DAQ Electronics Flight Buys

- Tower Power Supply Modules
- BAE RAD750 Processor Board
- Other Electronics components (Partslist to be submitted 2-7-02)
 - ACTEL FPGA
 - RT54SX32S-CQ208B
 - RT54SX72S-CQ208B
 - Others
 - Regulator OMNIREL OMR9601SCK
 - LVDS UTMC UT54LVDS032LV/UT54LVDS031LV
 - Inverter Intersil HCS14KMSR
 - UTMC 1553 5962R9466311QYA
 - Intersil POR IS-705RH
 - Honeywell SRAM IDT71256SA25Y
 - Connectors
 - Cristek MCR-1-069-1B1
 - Cristek MCR-1-051-1B1
 - ITT Cannon DDMA78PNM